

Product Specification

Product:	Conductive Silver Paste
Part Number:	01H-6602B

Application Scope :

A high viscosity and low fluidity silver paste is suitable for printing with small spacing and thick film layer, and also suitable for electromagnetic thermal conduction industry.

Usage Conditions :

Substrate	Ceramic, glass
Printing	200-300 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (the test temperature should not exceed 300°C; the baking time may be adjusted based on actual conditions).
Firing Condition	The sintering temperature is 700°C (recommended value) and the sintering time is 9-11 minutes. The sintering range can be adjusted between 550-750°C as needed, but the peak temperature must be maintained for 10 minutes.
Thinner	ST-1000

Characteristics :

1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	≤5μm	FOG test
2 Viscosity	250-450Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor model SC4-14/6R, operating at 10rpm and 25±1°C, with adjustable viscosity according to user requirements.

2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm.

Check fired film produced under the conditions specified in 1) , (Film thickness is 8-12μm.)

Characteristics		Standard	Test Method And Conditions
3	Resistivity	$\leq 5\text{m}\Omega/\square$	Test pattern 0.6mm×60mm
4	Adhesion Strength		Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.
	Initial Adhesion	$\geq 45.2\text{N}$	
	Ageing Adhesion	$\geq 24.6\text{N}$	Aging conditions: 150°C, 24 hours

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g per can.

Sample size: 200 g/can